STEP 1 Remove device from PCB. Wick or scavenge and clean part.

STEP 2 Place the part StencilMate ™ aligning it with part lands and applying pressure to the stencil. Squeegee solder paste with a manual squeegee into the apertures. Clean off surface of stencil.

STEP 3 Reflow paste based on solder manufacturer's profile.

STEP 4 Remove StencilMate™ from device clean and inspect

STEP 5 Inspect to make sure the “bumps” are uniform and consistent on all of the pads.